12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260518001.1
Qualify MLA as an additional Assembly site for select devices
Change Notification / Sample Request

Date: May 19, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260518001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	**CUSTOMER PART NUMBER**
DAC5578SPWR	DAC5578SPWR
TPA3007D1PWR	NULL
DRV10970PWPR	DRV10970PWPR
TLC5971PWPR	TLC5971PWPR
TPS54625PWPR	TPS54625PWPR
TPS55340PWPR	TPS55340PWPR
SN65HVS880PWPR	NULL
DAC7573IPW	DAC7573IPW
TPS54283PWPR	TPS54283PWPR
TPS54286PWPR	TPS54286PWPR
SN65HVS882PWPR	SN65HVS882PWPR
DAC8534IPWR	NULL
LM5176PWPR	NULL
TPS61194PWPR	TPS61194PWPR
TPS61199PWPR	TPS61199PWPR
TPS61199PWPR	595-TPS61199PWPR
DIR9001PWR	DIR9001PWR
TPS40057PWPR	NULL
TPS70102PWPR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260518001.1	**PCN Date:**	May 19, 2026
Title:	Qualify MLA as an additional Assembly site for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	August 17, 2026	**Sample requests accepted until:**	July 18, 2026*

***Sample requests received after** July 18, 2026 **will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/ Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Malaysia (MLA) as an additional Assembly site for the list of devices shown below. Material differences between sites as follows.

Group 1 Device (No material differences between sites)

	Current Site	Additional site
Assembly site	**TITL**	**MLA**

Group 2 Device

	Current Site	Additional site
Assembly site	**TITL**	**MLA**
Mount compound	4208458	4211470

Group 3 Device

	Current Site	Additional site
Assembly site	**TITL**	**MLA**
Mount compound	4042500	4147858
Mold compound	4206193	4211471

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site

TI Taiwan	Assembly Site Origin (22L)	ASO: TAI
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO:SHE (21L) CCO:USA
(22L) ASO:MLA (23L) ACO:MYS

Group 1 Product Affected:

BUF16821BIPWPR	DAC8534IPWR	TLV5608IPWR
DAC1282IPWR	DAC8574IPWR	TLV5608IPWR
DAC5578SPWR	DIR9001PWR	TPA3007D1PWR
DAC6573IPWR	DRV10970PWPR	TPA6030A4PWPR
DAC7564IAPWR	DRV604PWPR	TPS54625PWPR
DAC7564ICPWR	LM5175PWPR	TPS55340PWPR
DAC7564ICPWR	LM5176PWPR	TPS56720PWPR
DAC7565IAPWR	PCM1789PWR	TPS61194PWPR
DAC7565ICPWR	SN65HVS880PWPR	TPS61199PWPR
DAC7573IPW	TLC5971PWPR	TPS9361QPWPR
DAC7573IPWR	TLV1508IPWR	
DAC7678SPWR	TLV2548IPWR	

Group 2 Product Affected:

DRV11873PWPR	TPS40057PWPR	TPS54386PWPR
SN65HVS881PWPR	TPS40057PWPR	TPS70102PWPR
SN65HVS882PWPR	TPS54283PWPR	TPS70102PWPR
SN65HVS882PWPR	TPS54286PWPR	TPS73HD301PWPR
TLV2474IPWPR	TPS54383PWPR	TPS767D325PWPR
TPS40021PWPR	TPS54383PWPR	TPS92380PWPR
TPS40056PWPR	TPS54386PWPR	

Group 3 Product Affected:

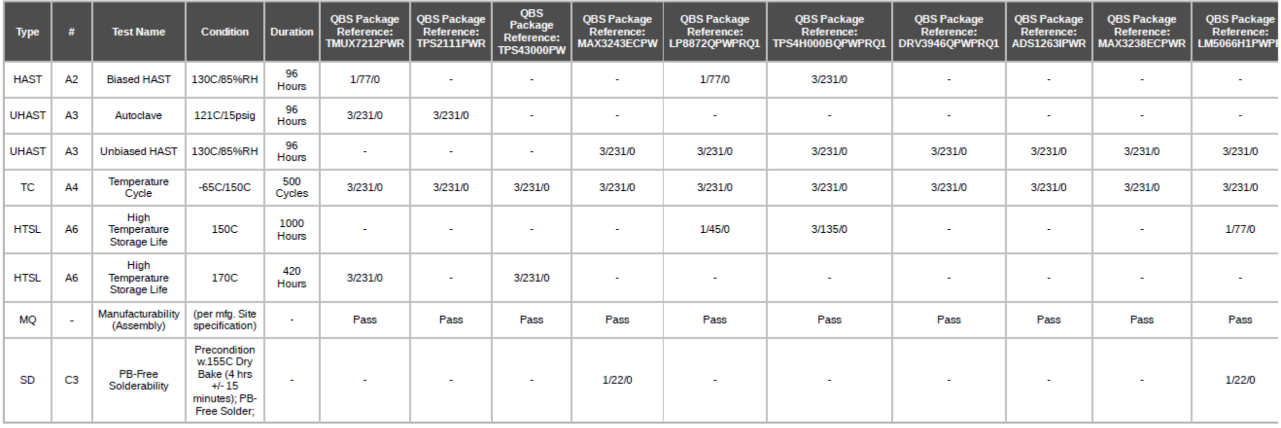
BQ7692003PWR	DAC1282AIPWR
BQ7692006PWR	SN7692003PWR

Qualification Report

Approve Date 13-MAY -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed



Type	#	Test Name	Condition	Duration	QBS Package Reference: TMUX7212PWR	QBS Package Reference: TPS2111PWR	QBS Package Reference: TPS43000PW	QBS Package Reference: MAX3243ECPW	QBS Package Reference: LP8872QPWPRQ1	QBS Package Reference: TPS4H000BQPWPRQ1	QBS Package Reference: DRV3946QPWPRQ1	QBS Package Reference: ADS1263IPWR	QBS Package Reference: MAX3238ECPWR	QBS Package Reference: LM5066H1PWP
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	1/77/0	3/231/0	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	-	-	-	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/45/0	3/135/0	-	-	-	1/77/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	3/231/0	-	-	-	-	-	-	-
MQ	-	Manufacturability (Assembly)	(per mfg. Site specification)	-	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	1/22/0	-	-	-	-	-	1/22/0

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2510-049

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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